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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

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Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, HLVD, I ² S, POR, PWM, WDT
Number of I/O	34
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx154f128d-i-ml

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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TABLE 5: PIN NAMES FOR 28-PIN USB DEVICES WITH VBAT

28-PIN	SOIC	(TOP	VIEW) ^(1,2,3)
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28

PIC32MX255F128B PIC32MX275F256B

Pin #	Full Pin Name	I	Pin #	Full Pin Name
1	MCLR		15	VBUS
2	PGED3/VREF+/AN0/C3INC/RPA0/ASDA1/CTED1/PMD7/RA0		16	TDI/RPB7/CTED3/PMD5/INT0/RB7
3	PGEC3/VREF-/AN1/RPA1/ASCL1/CTED2/PMD6/RA1		17	TCK/RPB8/SCL1/CTED10/PMD4/RB8
4	PGED2/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0		18	TDO/RPB9/SDA1/CTED4/PMD3/RB9
5	PGEC2/AN3/C1INC/C2INA/LVDIN/RPB1/CTED12/PMD1//RB1		19	Vss
6	PGED1/AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2		20	VCAP
7	PGEC1/AN5/C1INA/C2INC/RTCC/RPB3/SCL2/CTPLS/PMWR/RB3		21	D+
8	Vss		22	D-
9	OSC1/CLKI/RPA2/RA2		23	VUSB3V3
10	OSC2/CLKO/RPA3/PMA0/RA3		24	VBAT
11	SOSCI/RPB4/CTED11/RB4 ⁽⁴⁾		25	CVREFOUT/AN10/C3INB/RPB14/SCK1/CTED5/PMA1/RB14
12	SOSCO/RPA4/T1CK/CTED9/RA4		26	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
13	VDD		27	AVss
14	TMS/RPB5/USBID/PMRD/RB5		28	AVdd

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and 12.3 "Peripheral Pin Select" for restrictions.

2: Every I/O port pin (RAx-RBx) can be used as a change notification pin (CNAx-CNBx). See 12.0 "I/O Ports" for more information.

3: Shaded pins are 5V tolerant.

4: This is an input-only pin.

TABLE 1-13 :	USB PINOUT I/O DESCRIPTIONS
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	Pi	n Number ⁽¹	1,2)										
Pin Name	28-pin QFN	28-pin SOIC	44-pin QFN/ TQFP	Pin Type	Buffer Type	Description							
	Universal Serial Bus												
VBUS	12	15	42	I	Analog	USB Bus Power Monitor							
VUSB3V3	20	23	10	Р	—	USB Internal Transceiver Supply. This pin must be connected to VDD.							
VBUSON	PPS	PPS	PPS	0	—	USB Host and OTG Bus Power C	Control Output						
D+	18	21	8	I/O	Analog	USB D+							
D-	19	22	9	I/O	Analog	USB D-							
USBID	11	14	41	I	ST	USB OTG ID Detect							
USBON	14	17	44	0		ON Signal for External VBUS Sou	rce						
5	ST = Schmi	MOS compa tt Trigger in nput buffer		Analog = Analog input $P = P$ $O = Output$ $I = Inp$ $PPS = Peripheral Pin Select$ $= N$									

Note 1: Pin numbers are provided for reference only. See the "Pin Diagrams" section for device pin availability.

2: All pins are only available on USB devices.

3: Pin number for devices without VBAT.

4: Pin number for devices with USB only.

5: Pin number for devices without USB.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (VIH) and input low (VIL) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB[®] ICD 3 or MPLAB REAL ICE[™].

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site:

- "Using MPLAB[®] ICD 3" (poster) (DS50001765)
- "MPLAB[®] ICD 3 Design Advisory" (DS50001764)
- "MPLAB[®] REAL ICE™ In-Circuit Debugger User's Guide" (DS50001616)
- "Using MPLAB[®] REAL ICE™ Emulator" (poster) (DS50001749)

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (VIH) and input low (VIL) requirements.

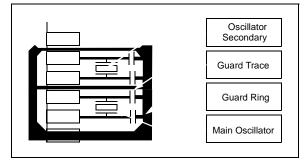
2.7 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: S

: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT



2.8 Unused I/Os

Unused I/O pins should not be allowed to float as inputs. They can be configured as outputs and driven to a logic-low state.

Alternatively, inputs can be reserved by connecting the pin to Vss through a 1k to 10k resistor and configuring the pin as an input.

TABLE 4-1: SFR MEMORY MAP

	Virtual A	Address			
Peripheral	Base	Offset Start			
Deep Sleep Controller		0x0000			
RTCC		0x0200			
Timer1-Timer5		0x0600			
Input Capture 1-5		0x2000			
Output Compare 1-5		0x3000			
I2C1 and I2C2		0x5000			
SPI1 and SPI2		0x5800			
UART1 and UART2		0x6000			
PMP		0x7000			
ADC	- 0xBF80	0x9000			
CVREF	UXDFOU	0x9800			
Comparator		0xA000			
CTMU		0xA200			
Oscillator, Reset		0xF000			
Device and Revision ID		0xF220			
Peripheral Module Disable		0xF240			
Flash Controller		0xF400			
Watchdog Timer		0xF600			
PPS		0xFA00			
HLVD		0xFC00			
Interrupts		0x1000			
Bus Matrix		0x2000			
DMA		0x3000			
Prefetch	0xBF88	0x4000			
USB		0x5000			
PORTA-PORTC		0x6000			
Configuration	0xBFC0	0x2FF0			

Interrupt Source ⁽¹⁾	IRQ	Vector		Persistent			
Interrupt Source	#	#	Flag	Enable	Priority	Sub-priority	Interrupt
U1E – UART1 Fault	39	32	IFS1<7>	IEC1<7>	IPC8<4:2>	IPC8<1:0>	Yes
U1RX – UART1 Receive Done	40	32	IFS1<8>	IEC1<8>	IPC8<4:2>	IPC8<1:0>	Yes
U1TX – UART1 Transfer Done	41	32	IFS1<9>	IEC1<9>	IPC8<4:2>	IPC8<1:0>	Yes
I2C1B – I2C1 Bus Collision Event	42	33	IFS1<10>	IEC1<10>	IPC8<12:10>	IPC8<9:8>	Yes
I2C1S – I2C1 Slave Event	43	33	IFS1<11>	IEC1<11>	IPC8<12:10>	IPC8<9:8>	Yes
I2C1M – I2C1 Master Event	44	33	IFS1<12>	IEC1<12>	IPC8<12:10>	IPC8<9:8>	Yes
CNA – PORTA Input Change Interrupt	45	34	IFS1<13>	IEC1<13>	IPC8<20:18>	IPC8<17:16>	Yes
CNB – PORTB Input Change Interrupt	46	34	IFS1<14>	IEC1<14>	IPC8<20:18>	IPC8<17:16>	Yes
CNC – PORTC Input Change Interrupt	47	34	IFS1<15>	IEC1<15>	IPC8<20:18>	IPC8<17:16>	Yes
PMP – Parallel Master Port	48	35	IFS1<16>	IEC1<16>	IPC8<28:26>	IPC8<25:24>	Yes
PMPE – Parallel Master Port Error	49	35	IFS1<17>	IEC1<17>	IPC8<28:26>	IPC8<25:24>	Yes
SPI2E – SPI2 Fault	50	36	IFS1<18>	IEC1<18>	IPC9<4:2>	IPC9<1:0>	Yes
SPI2RX – SPI2 Receive Done	51	36	IFS1<19>	IEC1<19>	IPC9<4:2>	IPC9<1:0>	Yes
SPI2TX – SPI2 Transfer Done	52	36	IFS1<20>	IEC1<20>	IPC9<4:2>	IPC9<1:0>	Yes
U2E – UART2 Error	53	37	IFS1<21>	IEC1<21>	IPC9<12:10>	IPC9<9:8>	Yes
U2RX – UART2 Receiver	54	37	IFS1<22>	IEC1<22>	IPC9<12:10>	IPC9<9:8>	Yes
U2TX – UART2 Transmitter	55	37	IFS1<23>	IEC1<23>	IPC9<12:10>	IPC9<9:8>	Yes
I2C2B – I2C2 Bus Collision Event	56	38	IFS1<24>	IEC1<24>	IPC9<20:18>	IPC9<17:16>	Yes
I2C2S – I2C2 Slave Event	57	38	IFS1<25>	IEC1<25>	IPC9<20:18>	IPC9<17:16>	Yes
I2C2M – I2C2 Master Event	58	38	IFS1<26>	IEC1<26>	IPC9<20:18>	IPC9<17:16>	Yes
CTMU – CTMU Event	59	39	IFS1<27>	IEC1<27>	IPC9<28:26>	IPC9<25:24>	Yes
DMA0 – DMA Channel 0	60	40	IFS1<28>	IEC1<28>	IPC10<4:2>	IPC10<1:0>	No
DMA1 – DMA Channel 1	61	41	IFS1<29>	IEC1<29>	IPC10<12:10>	IPC10<9:8>	No
DMA2 – DMA Channel 2	62	42	IFS1<30>	IEC1<30>	IPC10<20:18>	IPC10<17:16>	No
DMA3 – DMA Channel 3	63	43	IFS1<31>	IEC1<31>	IPC10<28:26>	IPC10<25:24>	No
		Lowes	t Natural O	rder Priority			

TABLE 7-1: INTERRUPT IRQ, VECTOR AND BIT LOCATION (CONTINUED)

Note 1: Not all interrupt sources are available on all devices. See TABLE 1: "PIC32MX1XX 28/44-Pin XLP (General Purpose) Family Features" and TABLE 2: "PIC32MX2XX 28/44-Pin XLP (USB) Family Features" for the lists of available peripherals.

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
24.24	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
31:24	—	—	—	_	_	F	RCDIV<2:0>	
00.40	R/W-0	U-0	R/W-y	U-0	U-0	U-0	U-0	U-0
23:16	DRMEN	—	SLP2SPD	_	_	—	—	—
45.0	U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
15:8	—		COSC<2:0>		_			
7.0	R/W-0	U-0	U-0	R/W-0	R/W-0, HS	R/W-y	R/W-y	R/W-y
7:0	CLKLOCK	—	—	SLPEN	CF	UFRCEN	SOSCEN	OSWEN ⁽¹⁾

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER

Legend:	y = Value set from Config	uration bits on POR	HS = Hardware Set
R = Readable bit	W = Writable bit	U = Unimplemented bit, re	ad as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-27 Unimplemented: Read as '0'

- bit 26-24 FRCDIV<2:0>: Internal Fast RC (FRC) Oscillator Clock Divider bits
 - 111 = FRC divided by 256 110 = FRC divided by 64
 - 101 = FRC divided by 32
 - 101 = FRC divided by 32100 = FRC divided by 16
 - 011 = FRC divided by 8
 - 010 = FRC divided by 010 = FRC divided by 4
 - 001 = FRC divided by 2
 - 000 = FRC divided by 1 (default setting)

bit 23 **DRMEN:** Dream Mode Enable bit

- 1 = Dream mode is enabled
- 0 = Dream mode is disabled
- bit 22 Unimplemented: Read as '0'
- bit 21 SLP2SPD: Sleep Two-speed Start-up Control bit
 - 1 = Use FRC as SYSCLK until the selected clock is ready
 - 0 = Use the selected clock directly
- bit 20-15 Unimplemented: Read as '0'
- bit 14-12 COSC<2:0>: Current Oscillator Selection bits
 - 111 = Reserved
 - 110 = Reserved
 - 101 = Internal Low-Power RC (LPRC) Oscillator
 - 100 = Secondary Oscillator (Sosc)
 - 011 = Reserved
 - 010 = Primary Oscillator (Posc) (HS or EC)
 - 001 = System PLL (SPLL)
 - 000 = Internal Fast RC (FRC) Oscillator divided by FRCDIV<2:0> bits (FRCDIV)
- bit 11 Unimplemented: Read as '0'
- **Note 1:** The reset value for this bit depends on the setting of the IESO bit (DEVCFG1<7>). When IESO = 1, the reset value is '1'. When IESO = 0, the reset value is '0'.

Note: Writes to this register require an unlock sequence. Refer to Section 42. "Oscillators with Enhanced PLL" (DS60001250) in the "PIC32 Family Reference Manual" for details.

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0					
04.04	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0					
31:24	ROTRIM<8:1>												
00.40	R/W-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0					
23:16	ROTRIM<0>	—	—	—	—	_	—	—					
45.0	U-0	R-0	U-0	U-0 U-0		U-0	U-0	U-0					
15:8	—	_	—	—	—	_	—	—					
7.0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0					
7:0				_				_					

REGISTER 8-6: REFOOTRIM: REFERENCE OSCILLATOR TRIM REGISTER

Legend:

0			
R = Readable bit	W = Writable bit	U = Unimplemented bit, I	read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-23 ROTRIM<8:0>: Reference Oscillator Trim bits

bit 22-0 Unimplemented: Read as '0'

Note 1: While the ON bit (REFO0CON<15>) is '1', writes to this register do not take effect until the DIVSWEN bit is also set to '1'.

 Do not write to this register when the ON bit (REFO0CON<15>) is not equal to the ACTIVE bit (REFO0CON<8>).

3: Specified values in this register do not take effect if RODIV<14:0> bits (REFO0CON<30:16>) = 0.

TABLE 12-4: PORTB REGISTER MAP

sse										Bits									
Virtual Address (BF88_#)	Virtual Addr (BF88_#) Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
6100	ANSELB	31:16	—		_	—	_	_	_	—	_	_	_	_	_	_	-		0000
0100	ANOLLD	15:0	ANSB15	ANSB14	ANSB13 ⁽³⁾	ANSB12 ⁽²⁾	_	-		—		—	—		ANSB3	ANSB2	ANSB1	ANSB0	EOOB
6110	TRISB	31:16	_	_		—		I		-			-						0000
0110	TRIBD	15:0	TRISB15	TRISB14	TRISB13 ⁽³⁾	TRISB12 ⁽²⁾	TRISB11 ⁽²⁾	TRISB10 ⁽²⁾	TRISB9	TRISB8	TRISB7	TRISB6 ⁽²⁾	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	FFFF
6120	PORTB	31:16	_	_		—		I		-			-						0000
0120	FORTB	15:0	RB15	RB14	RB13 ⁽³⁾	RB12 ⁽²⁾	RB11 ⁽²⁾	RB10 ⁽²⁾	RB9	RB8	RB7	RC6 ⁽²⁾	RB5	RB4	RB3	RB2	RB1	RB0	xxxx
6120	6130 LATB	31:16	—	_	—	—	—	—	—	—	—	_	—	—	—	—	—	_	0000
0130		15:0	LATB15	LATB14	LATB13 ⁽³⁾	LATB12 ⁽²⁾	LATB11 ⁽²⁾	LATB10 ⁽²⁾	LATB9	LATB8	LATB7	LATB6 ⁽²⁾	LATB5	LATB4	LATB3	LATB2	LATB1	LATB0	xxxx
01.40	0000	31:16	—	_	—	—	—	—	—	—	—	_	—	—	—	—	—	_	0000
6140	ODCB	15:0	ODCB15	ODCB14	ODCB13 ⁽³⁾	ODCB12 ⁽²⁾	ODCB11 ⁽²⁾	ODCB10 ⁽²⁾	ODCB9	ODCB8	ODCB7	ODCB6	ODCB5	ODCB4	ODCB3	ODCB2	ODCB1	ODCB0	0000
0450		31:16	—	_	_		_	_	_	—	_	_	_	_	_	_	—	_	0000
6150	CNPUB	15:0	CNPUB15	CNPUB14	CNPUB13 ⁽³⁾	CNPUB12(2)	CNPUB11 ⁽²⁾	CNPUB10 ⁽²⁾	CNPUB9	CNPUB8	CNPUB7	CNPUB6(2)	CNPUB5	CNPUB4	CNPUB3	CNPUB2	CNPUB1	CNPUB0	0000
0400		31:16	—	_	_		_	_	_	—	_	_	_	_	_	_	—	_	0000
6160	CNPDB	15:0	CNPDB15	CNPDB14	CNPDB13	CNPDB12(2)	CNPDB11 ⁽²⁾	CNPDB10 ⁽²⁾	CNPDB9	CNPDB8	CNPDB7	CNPDB6(2)	CNPDB5	CNPDB4	CNPDB3	CNPDB2	CNPDB1	CNPDB0	0000
0470		31:16	—	_	_		_	_	_	—	_	_	_	_	_	_	—	_	0000
6170	CNCONB	15:0	ON	_	SIDL		_	_	_	—	_	_	—	_	_	_	—	_	0000
0400		31:16	—	_	_		_	_	_	—	_	_	—	_	_	_	—	_	0000
6180	CNENB	15:0	CNIEB15	CNIEB14	CNIEB13(3)	CNIEB11 ⁽²⁾	CNIEB11(2)	CNIEB10(2)	CNIEB9	CNIEB8	CNIEB7	CNIEB6(2)	CNIEB5	CNIEB4	CNIEB3	CNIEB2	CNIEB1	CNIEB0	0000
		31:16	—	—	_	—	_	—	—	—	—	_	_	_	—	_	_	-	0000
6190	CNSTATB	15:0	CN STATB15	CN STATB14	CN STATB13 ⁽³⁾	CN STATB12 ⁽²⁾	CN STATB11 ⁽²⁾	CN STATB10 ⁽²⁾	CN STATB9	CN STATB8	CN STATB7	CN STATB6 ⁽²⁾	CN STATB5	CN STATB4	CN STATB3	CN STATB2	CN STATB1	CN STATB0	0000

Advance Information

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See 12.2 "CLR, SET and INV Registers" for more information.

2: This bit is not available on USB devices.

3: This bit is not available on VBAT devices.

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
31.24		—	—		—	_		—
00.40	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
23:16	—	—	—	-	—	_	_	—
15.0	R/W-0	U-0	R/W-0	R/W-0	R-0	U-0	R/W-0	R/W-0
15:8	ON ⁽¹⁾	—	SIDL	TWDIS	TWIP	_	TECS	<1:0>
7.0	R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0
7:0	TGATE		TCKPS	S<1:0>	_	TSYNC	TCS	_

REGISTER 13-1: T1CON: TYPE A TIMER CONTROL REGISTER

Legend:

R = Readable bit	W = Writable bit	U = Unimplemented bit, r	ead as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 Unimplemented: Read as '0'

- bit 15 **ON:** Timer On bit⁽¹⁾
 - 1 = Timer is enabled
 - 0 = Timer is disabled

bit 14 Unimplemented: Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit

1 = Discontinue module operation when the device enters Idle mode0 = Continue module operation when the device enters Idle mode

bit 12 **TWDIS:** Asynchronous Timer Write Disable bit

- 1 = Writes to Timer1 are ignored until pending write operation completes
- 0 = Back-to-back writes are enabled (Legacy Asynchronous Timer functionality)

bit 11 TWIP: Asynchronous Timer Write in Progress bit

In Asynchronous Timer mode:

- 1 = Asynchronous write to the Timer1 register in progress
- 0 = Asynchronous write to Timer1 register is complete
- In Synchronous Timer mode:

This bit is read as '0'.

- bit 10 Unimplemented: Read as '0'
- bit 9-8 TECS<1:0>: Timer1 External Clock Selection bits
 - 11 = Reserved
 - 10 = External clock comes from the LPRC
 - 01 = External clock comes from the T1CK pin
 - 00 = External clock comes from the SOSC

bit 7 **TGATE:** Timer Gated Time Accumulation Enable bit

When TCS = 1: This bit is ignored. When TCS = 0: 1 = Gated time accumulation is enabled

0 = Gated time accumulation is disabled

bit 6 Unimplemented: Read as '0'

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

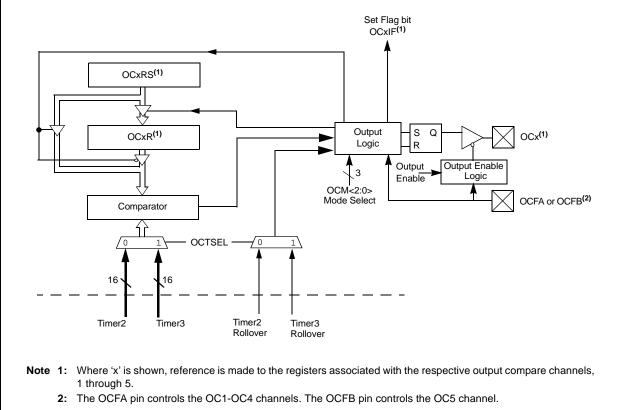
18.0 OUTPUT COMPARE

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/44-pin XLP Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to Section 16. "Output Compare" (DS60001111), which is available from the *Documentation* > *Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The Output Compare module is used to generate a single pulse or a train of pulses in response to selected time base events. For all modes of operation, the Output Compare module compares the values stored in the OCxR and/or the OCxRS registers to the value in the selected timer. When a match occurs, the Output Compare module generates an event based on the selected mode of operation. The following are some of the key features of the Output Compare module:

- Multiple Output Compare Modules in a device
- Programmable interrupt generation on compare event
- Single and Dual Compare modes
- Single and continuous output pulse generation
- Pulse-Width Modulation (PWM) mode
- Hardware-based PWM Fault detection and automatic output disable
- Can operate from either of two available 16-bit time bases or a single 32-bit time base





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Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0				
04-04	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0				
31:24	—	—	—	_	—	—	_	—				
00.40	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0				
23:16	—	—	—	—	—	—	-	—				
45.0	U-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0				
15:8	—	CS1	—	_	—	ADDR<10:8>						
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0				
	ADDR<7:0>											

REGISTER 22-3: PMADDR: PARALLEL PORT ADDRESS REGISTER

Legend:

5			
R = Readable bit	W = Writable bit	U = Unimplemented bit, I	read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-15 Unimplemented: Read as '0'

bit 14 CS1: Chip Select 1 bit

1 =Chip Select 1 is active

- 0 = Chip Select 1 is inactive
- bit 13-11 **Unimplemented:** Read as '0'
- bit 10-0 ADDR<10:0>: Destination Address bits

23.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/44-pin XLP Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to Section 29. "Real-Time Clock and Calendar (RTCC)" (DS60001125), which is available from the Documentation > Reference Manual section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32 RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

The RTCC module can operate in VBAT mode when there is a power loss on the VDD pin. The RTCC will continue to operate if the VBAT pin is powered on (it is usually connected to the battery). The following are some of the key features of the RTCC module:

- Time: hours, minutes and seconds
- 24-hour format (military time)
- · Visibility of one-half second period
- Provides calendar: day, date, month and year
- Alarm intervals are configurable for half of a second, one second, 10 seconds, one minute, 10 minutes, one hour, one day, one week, one month and one year
- · Alarm repeat with decrementing counter
- Alarm with indefinite repeat: Chime
- Year range: 2000 to 2099
- Leap year correction
- BCD format for smaller firmware overhead
- Optimized for long-term battery operation
- Fractional second synchronization
- User calibration of the clock crystal frequency with auto-adjust
- Calibration range: ±0.66 seconds error per month
- · Calibrates up to 260 ppm of crystal error
- Requirements: External 32.768 kHz clock crystal
- Alarm pulse or seconds clock output on RTCC pin

NOTES:

REGISTER 24-4: AD1CHS: ADC INPUT SELECT REGISTER (CONTINUED)

bit 20-16 CH0SA<4:0>: Positive Input Select bits for Sample A Multiplexer Setting

	11111 = Reserved
	•
	•
	•
	10010 = Reserved 10001 = Channel 0 positive input is VDD/2 10000 = Channel 0 positive input is VBAT 01111 = Reserved 01110 = Channel 0 positive input is IVREF ⁽¹⁾ 01101 = Channel 0 positive input is CTMU temperature sensor (CTMUT) ⁽²⁾ 01100 = Channel 0 positive input is AN12 ⁽³⁾
	•
	•
	•
	00001 = Channel 0 positive input is AN1 00000 = Channel 0 positive input is AN0
15-0	Unimplemented: Read as '0'

Note 1: See 26.0 "Comparator Voltage Reference (CVREF)" for more information.

- 2: See 28.0 "Charge Time Measurement Unit (CTMU)" for more information.
- 3: AN12 is only available on 44-pin devices. AN6-AN8 are not available on 28-pin devices.

bit

26.1 Comparator Voltage Reference Control Register

	TABLE 20-1. COMPARATOR VOLTAGE REFERENCE REGISTER MAP																		
ess		a a		Bits											ú				
Virtual Address (BF80_#)	Register Name ⁽¹⁾	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Reset
0000	CVRCON	31:16		—			—			—	—	—	—			_	_		0000
9800	CVRCON	15:0	ON	-		_	_	_	_	_	-	CVROE	CVRR	CVRSS		CVR<	3:0>		0000

TABLE 26-1: COMPARATOR VOLTAGE REFERENCE REGISTER MAP

Legend: x = unknown value on Reset; -- = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See 12.2 "CLR, SET and INV Registers" for more information.

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Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0			
24.24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0			
31:24	_	—	_	—	—	_	_	—			
00.40	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0			
23:16	_	—	—	—	—		_	—			
45.0	HC, R/W-y	U-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0			
15:8	DSEN ⁽¹⁾	—	DSGPREN	RTCDIS	—	_	_	RTCCWDIS			
7.0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0			
7:0	_	_			_	WAKEDIS	DSBOR ⁽²⁾	RELEASE			

REGISTER 29-1: DSCON: DEEP SLEEP CONTROL REGISTER

Legend:	HC = Hardware Cleared	y = Value set from Configuration bits on POR
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
-n = Value at POR	'1' = Bit is set	0' = Bit is cleared $x = Bit is unknown$

bit 31-16 Unimplemented: Read as '0'

- bit 15 **DSEN:** Deep Sleep Enable bit⁽¹⁾
 - 1 = Deep Sleep mode is entered on a WAIT command
 - 0 = Sleep mode is entered on a WAIT command
- bit 14 Unimplemented: Read as '0'

bit 13 **DSGPREN:** General Purpose Registers Enable bit

- 1 = General purpose register retention is enabled in Deep Sleep mode
- 0 = No general purpose register retention in Deep Sleep mode

bit 12 RTCDIS: RTCC Module Disable bit

- 1 = RTCC module is not enabled
- 0 = RTCC module is enabled
- bit 11-9 Unimplemented: Read as '0'
- bit 8 RTCCWDIS: RTCC Wake-up Disable bit
 - 1 = Wake-up from RTCC is disabled
 - 0 = Wake-up from RTCC is enabled

bit 7-3 Unimplemented: Read as '0'

- bit 2 WAKEDIS: Wake-up Source Disable bit
 - 1 = External wake-up source is disabled
 - 0 = External wake-up source is enabled
- bit 1 DSBOR: Deep Sleep BOR Event Status bit⁽²⁾
 - 1 = DSBOREN was enabled and VDD dropped below the DSBOR threshold during Deep Sleep⁽²⁾ 0 = DSBOREN was disabled, or VDD did not drop below the DSBOR threshold during Deep Sleep

bit 0 **RELEASE:** I/O Pin State Release bit

- 1 = Upon waking from Deep Sleep, the I/O pins maintain their previous states
- 0 = Release I/O pins and allow their respective TRIS and LAT bits to control their states
- Note 1: To enter Deep Sleep mode, Sleep mode must be executed after setting the DSEN bit.
 - 2: Unlike all other events, a Deep Sleep Brown-out Reset (BOR) event will not cause a wake-up from Deep Sleep mode; this bit is present only as a status bit.

TABLE 33-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHA	ARACTER	ISTICS	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$								
Param. No.	Symbol	Characteristics	Min.	Тур.	Max.	Units	Conditions				
Operating Voltage											
DC10	Vdd	Supply Voltage (Note 2)	2.5		3.6	V	—				
DC12	Vdr	RAM Data Retention Voltage (Note 1)	2.0	_	—	V	_				
DC16	VPOR	VDD Start Voltage (Note 3) to Ensure Internal Power-on Reset Signal	1.75	_	2.1	V	_				
DC17	SVDD	VDD Rise Rate to Ensure Internal Power-on Reset Signal	0.00005	_	0.115	V/µs	_				
DC18	VBAT	Battery Supply Voltage	1.94	_	3.6	V	—				

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 33-5 for BOR values.

3: VDD voltage must remain below VPOR for a minimum of 200 µs to ensure POR.

TABLE 33-5: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS				$\begin{array}{llllllllllllllllllllllllllllllllllll$							
Param. No.	Symbol	ool Characteristics		Тур.	Max.	Units	Conditions				
BO10 VBOR BOR Event on VDD transition high-to-low (Note 2)			2.2		2.384	V	_				

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN.

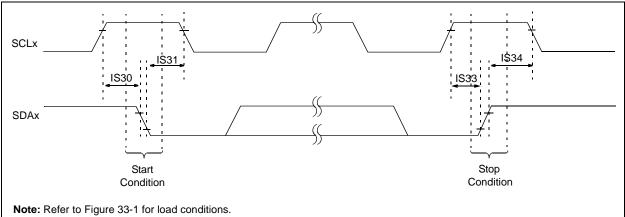
TABLE 33-8: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

TABLE 00 0.	200000									
DC CHARACT	ERISTICS		$\begin{array}{llllllllllllllllllllllllllllllllllll$							
Parameter No.	Typical ⁽²⁾	Max.	Units	Units Conditions						
Idle Current (IIDLE): Core Off, Clock on Base Current (Notes 1, 4)										
DC30a	0.6	_	mA	4 MHz (Note 3)						
DC31a	1.5	_	mA		10 MHz					
DC32a	4.5	—	mA		30 MHz (Note 3)					
DC33a	7.5	_	mA		50 MHz (Note 3)					
DC34a	10.5	_	mA		72 MHz					
DC37a	100	_	μA	-40°C		LPRC (31 kHz)				
DC37b	250		μA	+25°C	3.3V	(Note 3)				
DC37c	380		μA	+85°C	1					

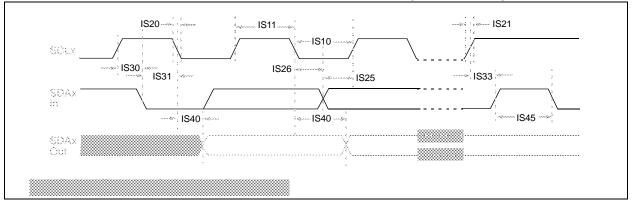
Note 1: The test conditions for IIDLE current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Idle mode (CPU core Halted), and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to Vss
- $\overline{\text{MCLR}}$ = VDD
- RTCC and JTAG are disabled
- 2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- **3:** This parameter is characterized, but not tested in manufacturing.
- 4: IIDLE electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.









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NOTES: